


# MATERIAL DECLARATION SHEET



Material Number	CM453232 Series			
Product Line	Wound Chip Inductor			
Compliance Date	2016 / 06 / 17			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	T2F	0.028	Iron oxide	1309-37-1	63.0	16.913	26.846
				Nickel oxide	1313-99-1	12.0	3.221	
				Zinc oxide	1314-13-2	18.0	4.832	
				Copper oxide	1317-38-0	7.0	1.879	
2	Winding Wire	P180-G2	0.015	Copper	7440-50-8	95.0	13.663	14.382
				Polyester Resin	9009-54-5	5.0	0.719	
3	Terminal	TC LEAD	0.035	Copper	7440-50-8	95.0	31.879	33.557
				Tin	7440-31-5	5.0	1.678	
4	Adhesive	S-F1-610W	0.012	Poly[(phenyl glycidyl ether)-co-formaldehyde]	28064-14-4	70.0	8.054	11.505
				2-Methylimidazole	693-98-1	6.0	0.690	
				Carbon black	1333-86-4	4.0	0.460	
				Silicon dioxide	7631-86-9	20.0	2.301	
5	Adhesive	1010-42A	0.0054	Bisphenol A diglycidyl ether	25068-38-6	82.0	4.246	5.177
		5524-2B	0.0027	1,4-Butanediol diglycidyl ether	2425-79-8	18.0	0.932	
				Methyltetrahydrophthalic anhydride	26590-20-5	95.0	2.459	2.589
6	Molding compound	1100RG	0.0042	Silica	14808-60-7	69.0	2.779	4.027
				Antimony trioxide	1309-64-4	2.5	0.101	
				Epoxy Resin	29690-82-2	15.0	0.604	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.403	
				Brominated epoxy resin	40039-93-8	2.5	0.101	
				Carbon black	1333-86-4	1.0	0.040	

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7	Solder	100H	0.002	Tin (Sn)	7440-31-5	100.0	1.917	1.917
		Total weight	<b>0.1043</b>					

**This Document was updated on: 2016/06/17**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.